



# Material Composition Declaration

## EPC2038

Company Name	Efficient Power Conversion (EPC)	Issue Date:	9/22/2017
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	1.3 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	1.1602	87.5805	90.0848	875805
	Silicon oxide	7631-86-9	0.0052	0.3936		3936
	Silicon nitride	12033-89-5	0.0017	0.1275		1275
	Gallium nitride	25617-97-4	0.0062	0.4680		4680
	Aluminum	7429-90-5	0.0084	0.6378		6378
	Aluminum nitride	24304-00-5	0.0014	0.1091		1091
	Titanium	7440-32-6	0.0002	0.0161		161
	Titanium nitride	25583-20-4	0.0010	0.0769		769
	Copper	7440-50-8	0.0003	0.0212		212
	Tungsten	7440-33-7	0.0000	0.0031		31
	Polyimide		0.0086	0.6511		6511
Under Bump Metal	Titanium	7440-32-6	0.0001	0.0060	0.5098	60
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.0067	0.5038		5038
Solder Bump	Tin	7440-31-5	0.1190	8.9822	9.4054	89822
	Silver	7440-22-4	0.0050	0.3762		3762
	Copper	7440-50-8	0.0006	0.0470		470
Sum in total:			1.3247	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.